Contribution ID: **105** Type: **Poster not shown**

Studies of Interconnect Technologies for HEP Applications

HEP detectors are continually moving towards higher segmentation of elements and higher complexity in assembly architectures. The task of interconnecting detector elements with readout electronics and with readout buses for such detectors poses new challenges and opportunities. We will address progress on several fronts: anisotropic conducting films, conductive epoxy stencils, flexible cable attachments, and gold stud bonding. Our work is aimed at generic R&D but focused towards detectors for the ILC and Super LHC.

Summary (Additional text describing your work. Can be pasted here or give an URL to a PDF document):

ftp://ftp.irving.org/pub/users/dirving/Irving_Vienna_Conference.pdf

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